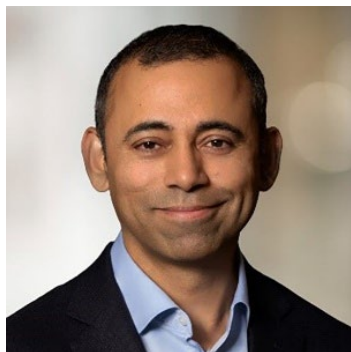


Powering DRAM and Advanced Packaging Inflections

with Materials Innovation and Process Control



KEVIN MORAES, PH.D.

*Corporate Vice President
Strategy and Marketing, Semiconductor Products Group*

Kevin leads Applied Materials' global strategy and marketing initiatives, driving growth across key semiconductor segments. He focuses on aligning market insights with business priorities, shaping competitive positioning, and enabling customer success through technology inflections. Prior to his current role, Kevin held leadership positions across product management and technology development at Applied. He holds a Bachelor's degree in Chemical Engineering from Annamalai University, an MBA from UC Berkeley, and a Ph.D. in Materials Science and Engineering from Rensselaer Polytechnic Institute.

Powering DRAM and Advanced Packaging Inflections

with Materials Innovation and Process Control



SONY VARGHESE, PH.D.

*Managing Director
Technology Strategy, Semiconductor Products Group*

Dr. Sony Varghese is Managing Director of Technology Strategy for Next gen products in the Semiconductor Products Group at Applied Materials. In this role, he is involved in identifying future key inflections and challenges to scaling advanced semiconductors in Applied's implant and patterning business unit. Prior to Applied Materials, he worked on developing various memory technologies within the R&D organization at Micron Technologies. Dr. Varghese has over 60 U.S. patents issued or pending in the area of semiconductor processing and integration. He has a Ph.D. in Materials and Mechanical Engineering from Oklahoma State University.

Powering DRAM and Advanced Packaging Inflections

with Materials Innovation and Process Control



JINHO AN, PH.D.

*Senior Director
Heterogeneous Integration, Semiconductor Products Group*

Jinho An is a Senior Director in the Heterogeneous Integration Business Unit and has been working at Applied Materials as an Account Technologist since 2021. Prior to Applied, he was a process and integration R&D engineer at Samsung Electronics working on wafer level advanced packaging technology and product development including HBM, HD FOWLP, interposers and CIS. Jinho has a B.S. in inorganic materials engineering from Hanyang University and a Ph.D. in materials science and engineering from the University of Texas at Austin.

Powering DRAM and Advanced Packaging Inflections

with Materials Innovation and Process Control



LIOR ENGEL

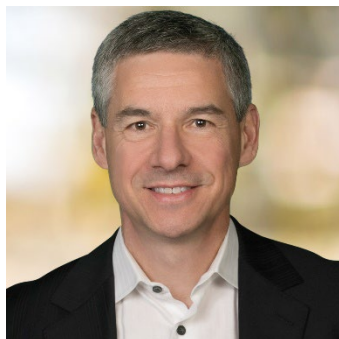
*Corporate Vice President
Imaging and Process Control Group*

Lior Engel oversees product development, marketing, and applications strategy for Metrology and Inspection Products at Applied Materials. In this role, he drives the convergence of advanced measurement capabilities with Applied Materials' process technologies — enabling customers to accelerate time to market and achieve superior device performance at scale.

With more than 25 years of experience in the semiconductor metrology and inspection industry, Mr. Engel brings deep domain expertise spanning eBeam-based defect review, wafer inspection, and advanced process control. He joined Applied Materials through the acquisition of Orbot Instruments and has since held progressively senior roles across applications, product marketing, and general management.

Powering DRAM and Advanced Packaging Inflections

with Materials Innovation and Process Control



MICHAEL SULLIVAN

*Corporate Vice President
Head of Investor Relations*

Michael Sullivan is Corporate Vice President and head of Investor Relations. His team is responsible for investor relations and marketing communications including media relations, product and technology communications, and industry events. Mr. Sullivan joined Applied in 2009 after working at Intel Corporation for 16 years. He was Intel's primary interface to equity analysts and the company's largest institutional shareholders in the U.S. and Europe. He also held corporate communications positions at the company's U.S. and European offices, where he drove corporate and competitive initiatives, new microprocessor introductions, computing platform campaigns, and flash memory PR. Mr. Sullivan is past president of the Silicon Valley chapter of NIRI, the National Investor Relations Institute. He earned his MBA at Santa Clara University and his BA in Public Relations at San Jose State University.